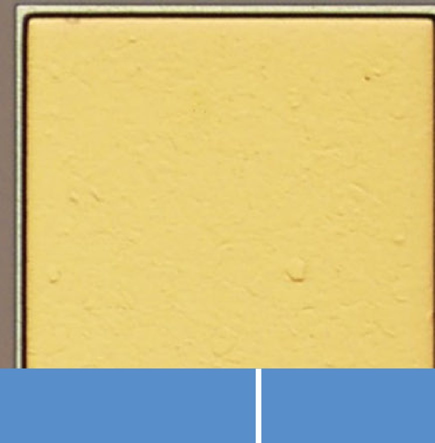
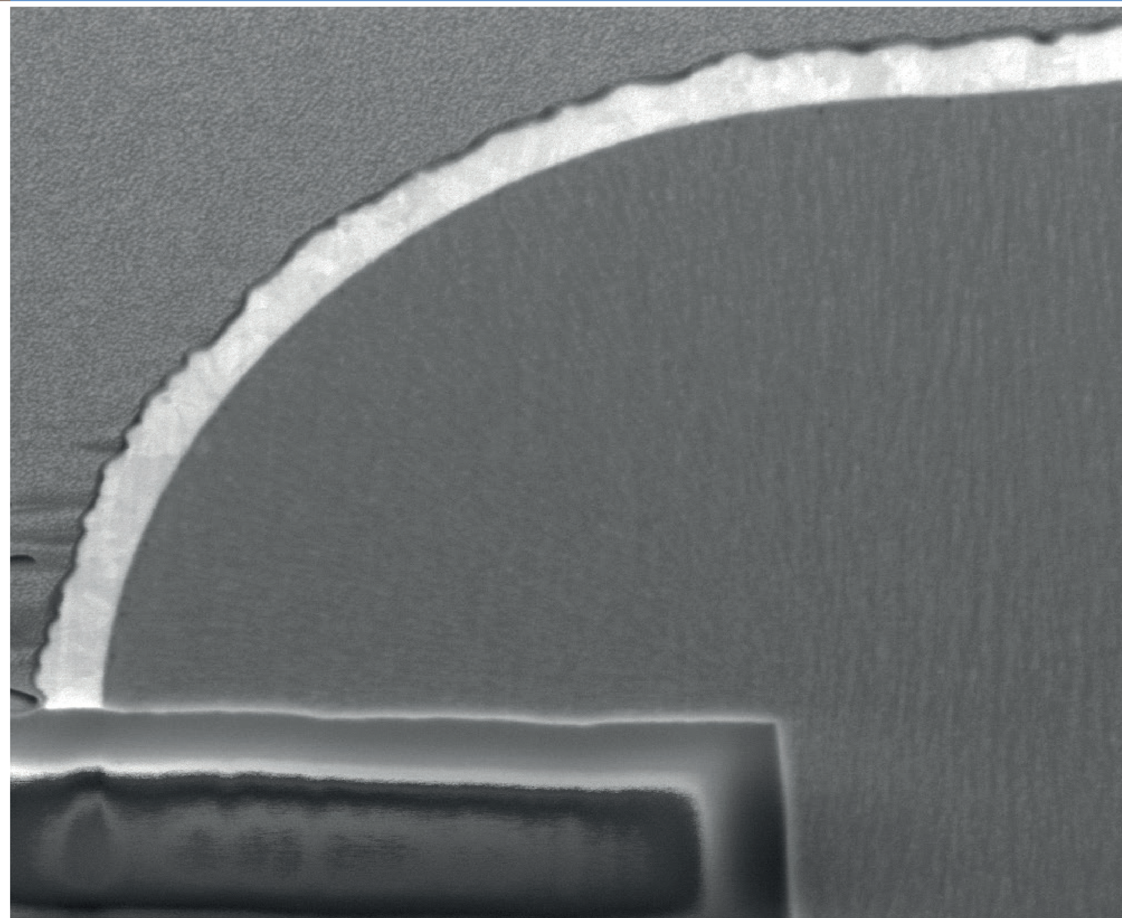
Xenolyte® Au TG

mks Atotech

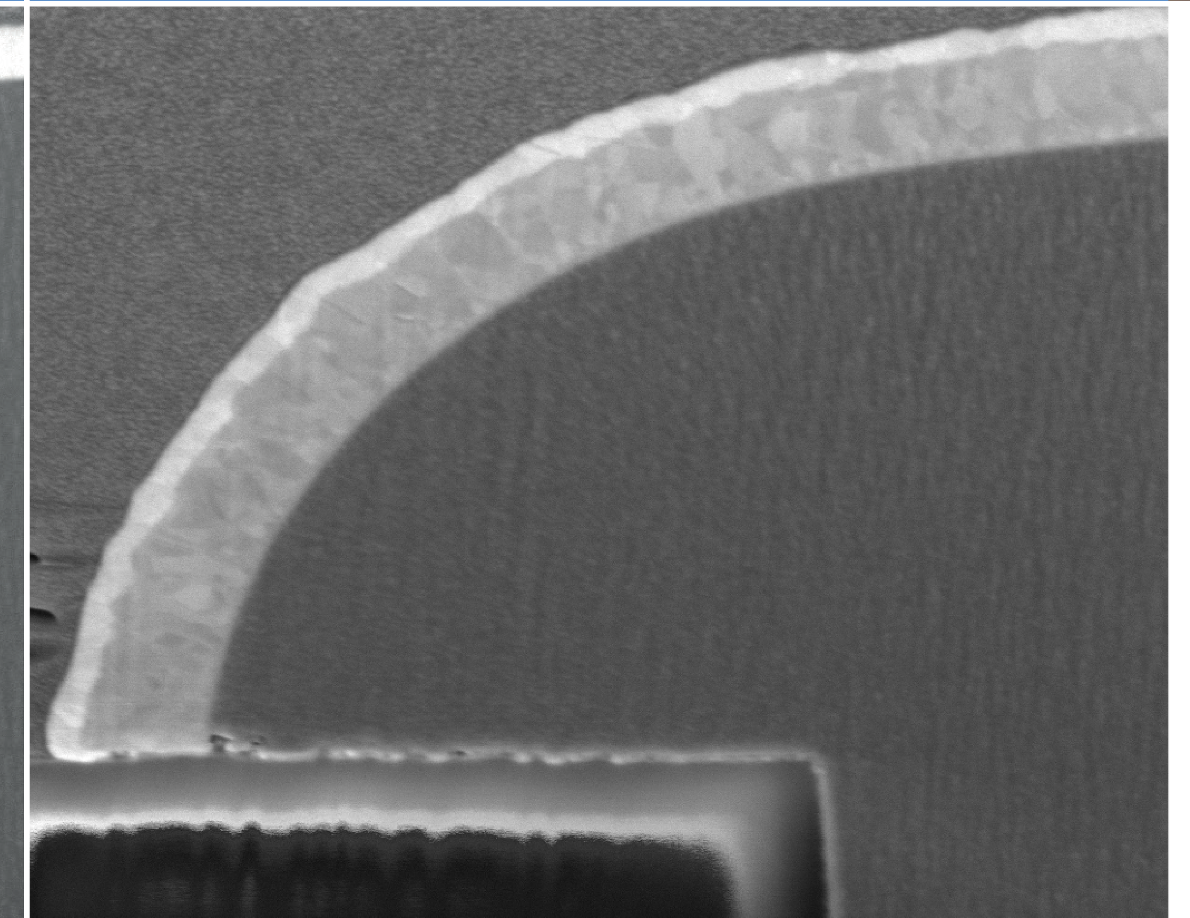
Autocatalytic Au process – A final finish on Ni or Pd for RDL and pad metallisation

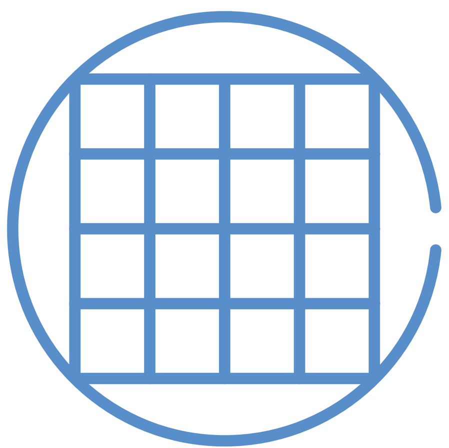


200 nm Xenolyte® Au TG on 3 µm NiP

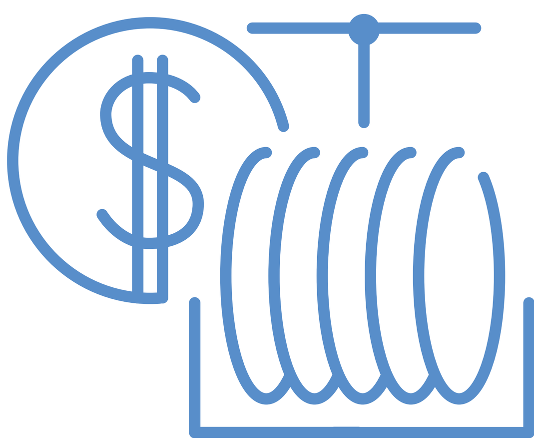


120 nm Xenolyte® Au TG on 400 nm pure Pd and 3 µm NiP





One step autocatalytic Au process for thick Au deposits



Compatible with batch processing in wet bench

Autocatalytic Au for automotive and power IC customers

Our pure autocatalytic Au process Xenolyte® Au TG is the perfect addition to our electroless RDL and pad metallization portfolio. It provides thick and pure gold deposits on electroless nickel and palladium layers. The deposition of thick Au layers from Xenolyte® Au TG does not require an immersion Au strike step and thus reduces corrosion of underlying metal layers to a minimum.

Features and benefits

- Pure gold deposits
- No immersion Au prestrike step required
- Deposition rates between 5-15 nm/min
- Extended bath lifetime
- Applicable to electroless Ni and Pd layers
- Suitable for soldering and wire bonding applications
- Cyanid-, EDTA-, and aldehyde-free